



Material Declaration Sheet

Vishay General Semiconductor - PDD

Date 28/Jul/20

Part / Product Family Details

Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemptions Used
ES1A-(H)E3 to ES1K-(H)E3 ESH1A-(H)E3 to ESH1D-(H)E3 RS1A-(H)E3 to RS1K-(H)E3 S1A-(H)E3 to S1M-(H)E3 S1BA-(H)E3 to S1MA-(H)E3 SA2B-E3 to SA2M-E3 SML4728-(H)E3 to SML4764A-(H)E3 US1A-(H)E3 to US1G-(H)E3 US1J-(H)E3 to US1M-(H)E3 CS1D, CS1G, CS1J, CS1K, CS1M-(H)E3 CSA2D, CSA2G, CSA2J, CSA2K, CSA2M-(H)E3	YES WITH EXEMPTION	01-12-2004	0.064	N/A	Yes	China	Two

Technical Information: refer to <http://www.vishay.com/low/leadfree/summary>

Terminal Plating / Grid Array Material	Terminal Base Alloy	JESD-97 Pb-Free Material Code Marking	J-STD-20D MSL Rating	Reflow Peak Process Body Temperature	Reflow Maximum number of cycles	Reflow Max. Time at Peak Temperature (sec)	Soldering Compatibility (SnPb/Pb-Free)

Material Composition

Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm		
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00130	100.00	1000000	2.03	Exemption No:7(c)-I
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.02300	100.00	1000000	35.94	
Solder 92.5	Other special metals	Lead	7439-92-1	0.00231	92.50	925000	3.61	Exemption No:7(a)
		Tin	7440-31-5	0.00013	5.00	50000	0.20	
		Silver	7440-22-4	0.00006	2.50	25000	0.10	
Encapsulation	Other duromers	Quartz (SiO2)	14808-60-7	0.02492	70.00	700000	38.93	
		Epichlorohydrin, o-cresol, formalde polymer	29690-82-2	0.00569	16.00	160000	8.89	
		Phenol-formaldehyde resin	9003-35-4	0.00427	12.00	120000	6.68	
		Antimony oxide (Sb2O3)	1309-64-4	0.00036	1.00	10000	0.56	
		Carbon-Black	1333-86-4	0.00009	0.25	2500	0.14	
		Additive & know-how	-	0.00027	0.75	7500	0.42	
Surface finish	Other special metals	Tin	7440-31-5	0.00160	100.00	1000000	2.50	

EU-RoHS Directive-2015/863/EU MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium, Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP)

This MDS valid for List of PN's

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

2nd Exemption Used 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.
(ii) Substance weight are derived from MSDS.

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